

Title (en)

Process for manufacturing interconnectable building parts and set of building parts with connecting elements

Title (de)

Verfahren zur Herstellung von miteinander verbindbaren Bauteilen sowie Anordnung von Bauteilen mit Verbindungselementen

Title (fr)

Procédé de fabrication de pièces interconnectables et ensemble de pièces avec des éléments de connexion

Publication

**EP 1527240 B1 20080702 (DE)**

Application

**EP 03732391 A 20030516**

Priority

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- EP 0305139 W 20030516

Abstract (en)

[origin: US2004016197A1] An arrangement of building elements capable of a snap-fastening interconnection comprises an element, especially the tongue, consisting of a different material from the other building elements. An MDF/HDF panel, is initially milled along the longitudinal and/or transverse sides, and the resulting groove is then provided and/or foam-filled with extrudates. Finally, the free ends of the extrudates are milled to form the profile of the tongue. Alternatively, or additionally, a groove may also be milled into the extrudates.

IPC 8 full level

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CPC (source: EP US)

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